Contents

Revisions

Rev	Description	Date	Approved
X1	First Release	23Mar12	M Kamil
X2	1. Some parts changed with Alternates suggested by Juan 2. Socket part number changed to 210-79953 3. Project name changed to XTWR-56F8200 4. J501 Footprint changed to CON220_SSM_MIRRORED	03APR12	M Kamil & JUAN
	A070 Release	04Apr12	SHANU & JUAN
A	J501 Footprint changed to CON220_SSM_MIRRORED_PL	18Apr12	KAMIL & JUAN
	A085 RELEASE	18Apr12	KAMIL & JUAN
B	U3 - sub-assy 750-77330 made DNP Project name changed to TWR-56F8200	04Jan13	ARMAS JUAN
	A085 RELEASE	10Jan13	ARMAS JUAN
B1	MCU silicon PN changed to PC56F82748VLH A085 RELEASE	06FEB13	ARMAS JUAN

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ICAP Classification: FCP: FIUO: X PUBI:

Designer: Shanu Gupta	Drawing Title: **TWR-56F8200**	
Drawn by: Shanu Gupta	Page Title: **Table of Contents/Revisions**	
Approved: M Kamil	Size C / Document Number SCH-27546 PDF: SPF-27546	Rev B1
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ecified:
ohms
All voltages are DC

2. Interrupted lines coded with the same letter or letter combinations are electrically connected.

3. Device type number is for reference only. The number varies with the manufacturer.

4. Special signal usage:
   _B Denotes - Active-Low Signal
   <> or [] Denotes - Vectored Signals

5. Interpret diagram in accordance with American National Standards Institute specifications, current revision, with the exception of logic block symbology.

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Drawing Title: **TWR-56F8200**

Page Title: **Notes**

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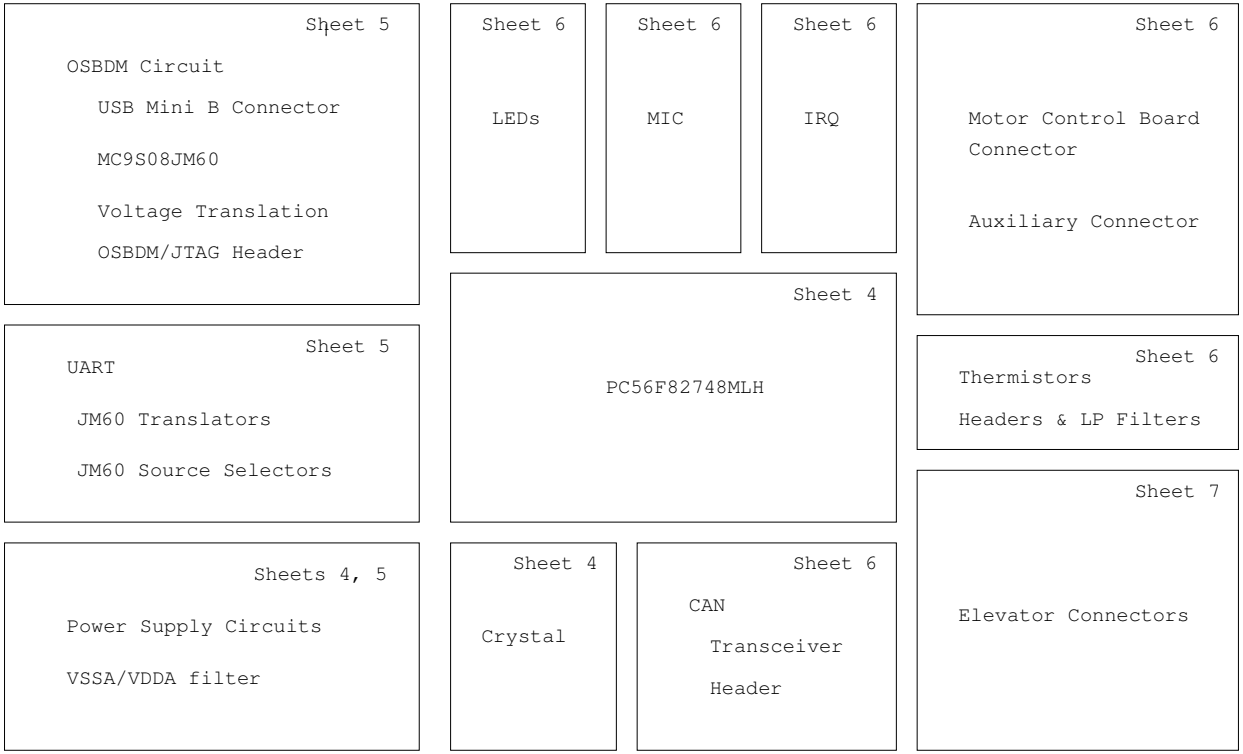

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Page Title: **Block Diagram**

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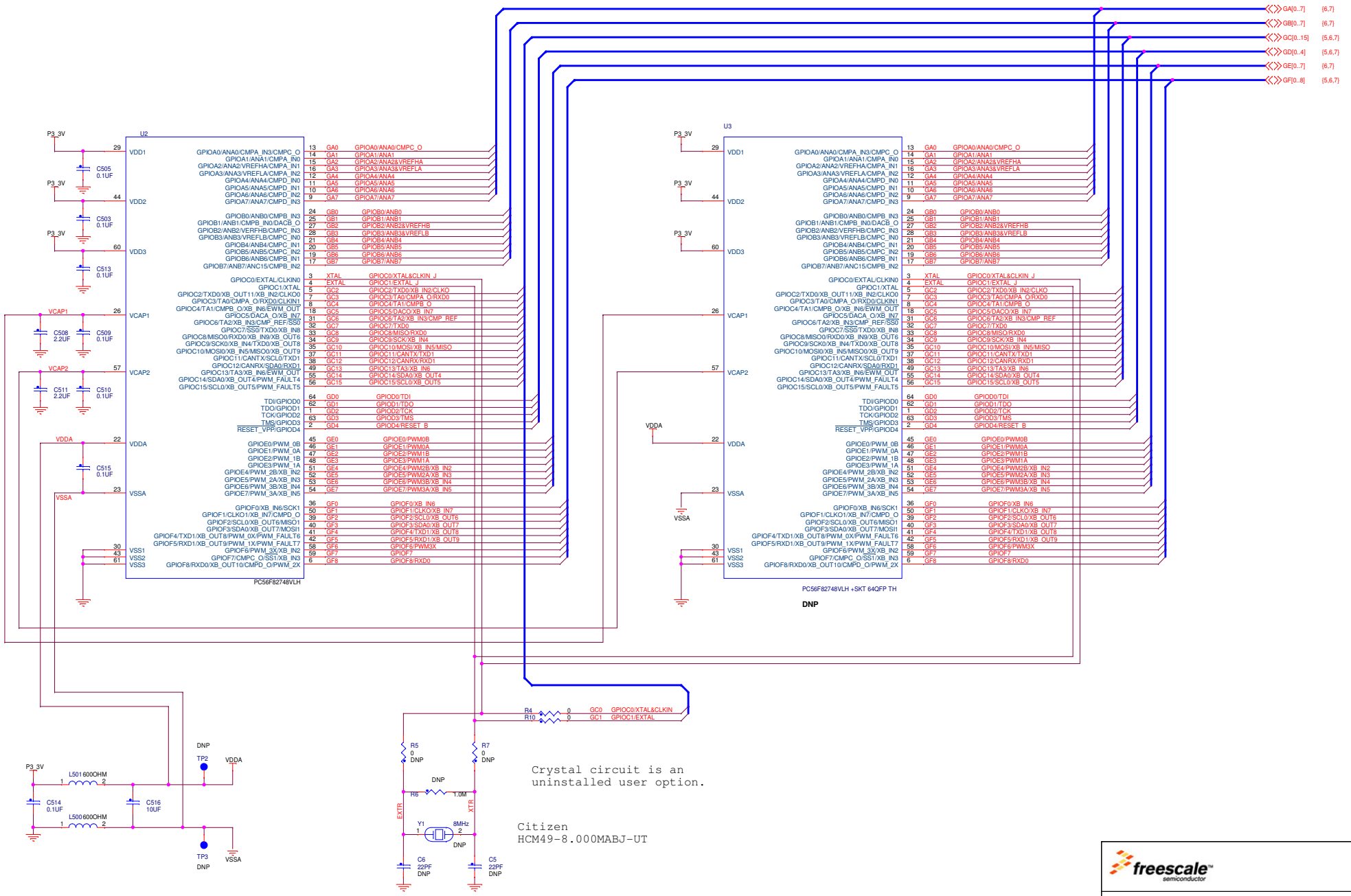
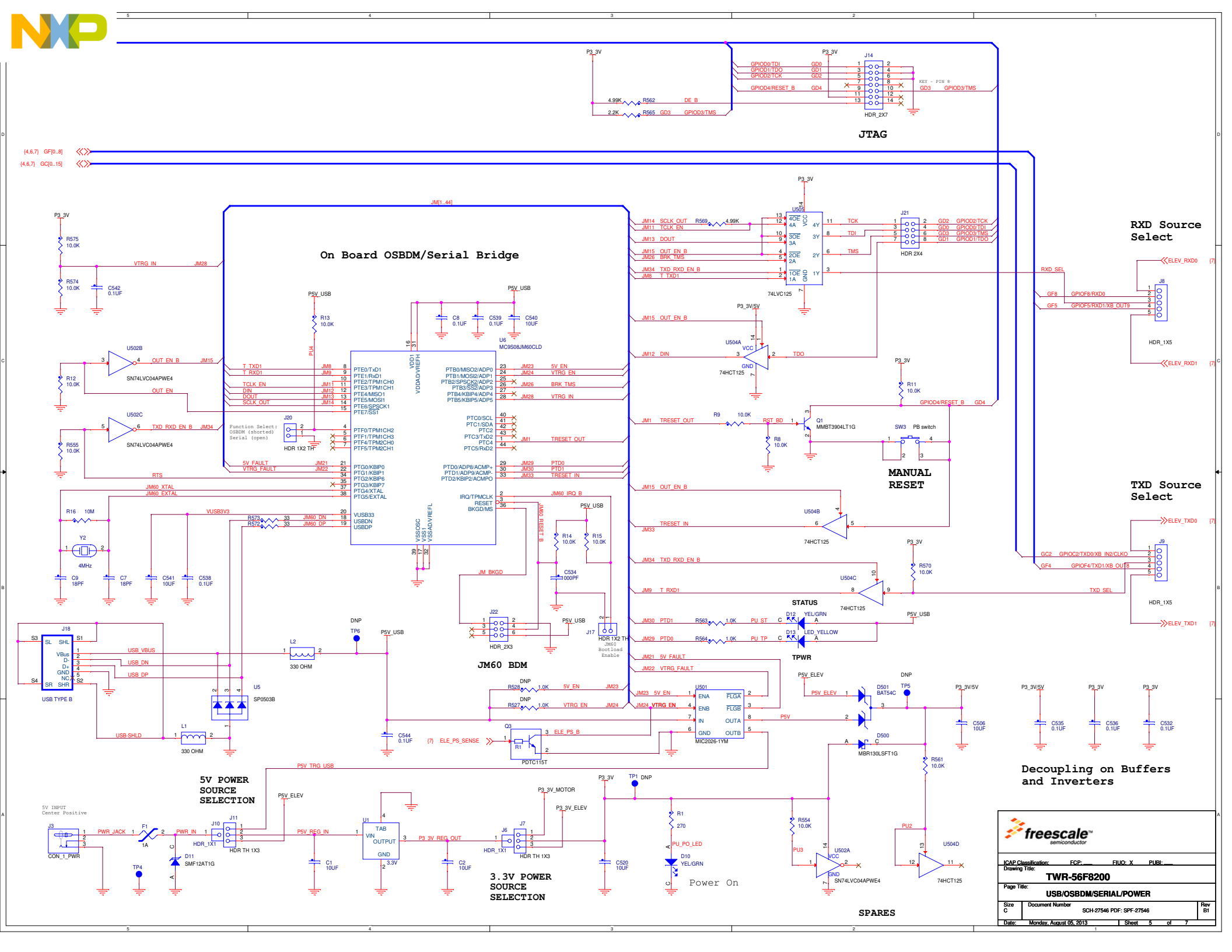
The DSC footprint and the ZIF socket are concentric on the board. Boards are built with a surface mounted DCS or with the DSC in the socket - not both.




JTAG
On Board OSBDM/Serial Bridge
RXD Source Select
TXD Source Select
MANUAL RESET
STATUS
TPWR
JM60 BDM
5V POWER SOURCE SELECTION
3.3V POWER SOURCE SELECTION
Decoupling on Buffers and Inverters
SPARES
Power On
USB TYPE B
5V INPUT Center Positive
ICAP Classification: FCP: ___ FIUO: X PUBI: ___
Drawing Title: TWR-56F8200
Page Title: USB/OSBDM/SERIAL/POWER
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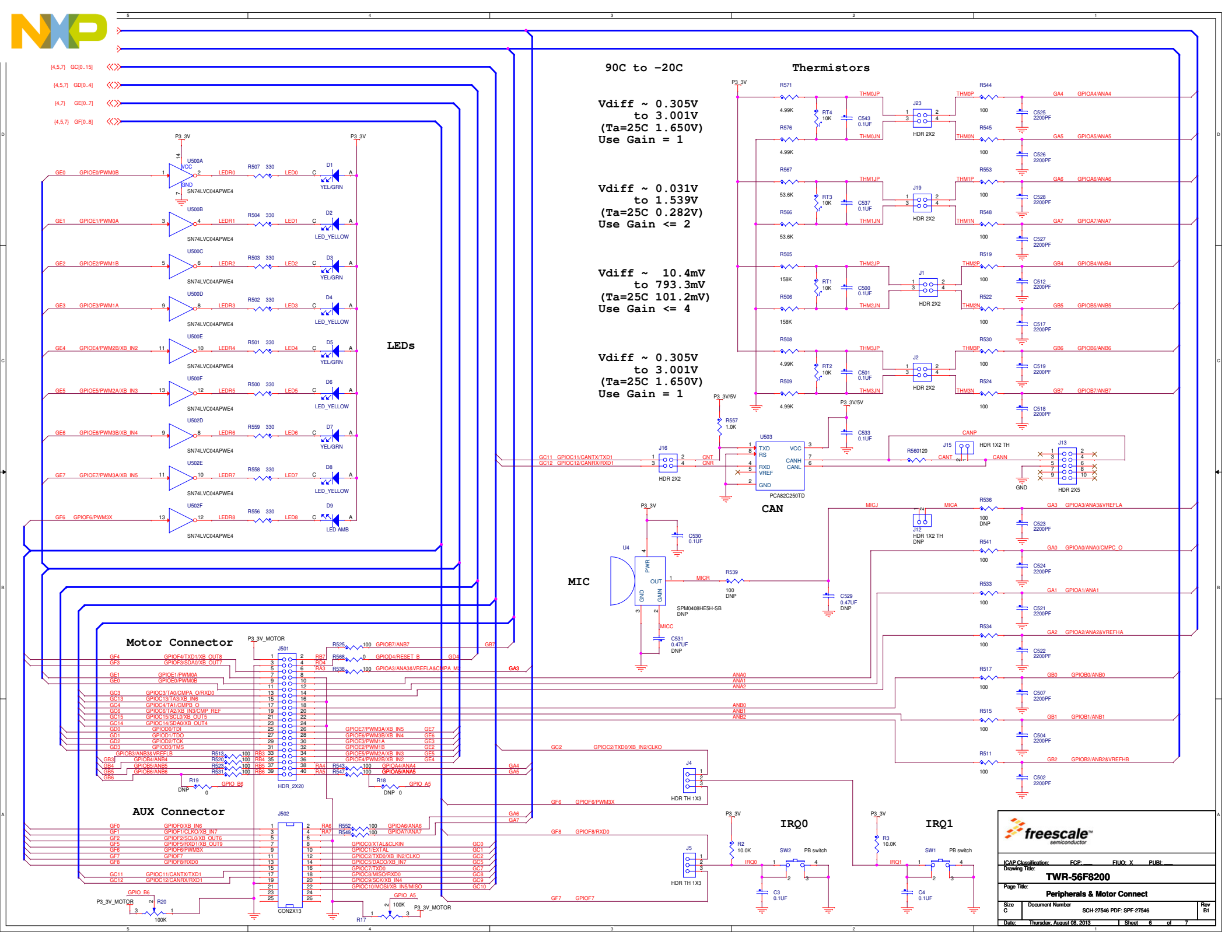
LEDs
Thermistors
90C to -20C
Vdiff ~ 0.305V
to 3.001V
(Ta=25C 1.650V)
Use Gain = 1
Vdiff ~ 0.031V
to 1.539V
(Ta=25C 0.282V)
Use Gain <= 2
Vdiff ~ 10.4mV
to 793.3mV
(Ta=25C 101.2mV)
Use Gain <= 4
Vdiff ~ 0.305V
to 3.001V
(Ta=25C 1.650V)
Use Gain = 1
CAN
MIC
Motor Connector
AUX Connector
IRQ0
IRQ1
SN74LVC04APWE4
YEL/GRN
LED_YELLOW
LED AMB
PCA82C250TD
SPM0408HE5H-SB
HDR 2X2
HDR 2X5
HDR 1X2 TH
HDR TH 1X3
HDR_2X20
CON2X13
PB switch
freescale semiconductor
TWR-56F8200
Peripherals & Motor Connect
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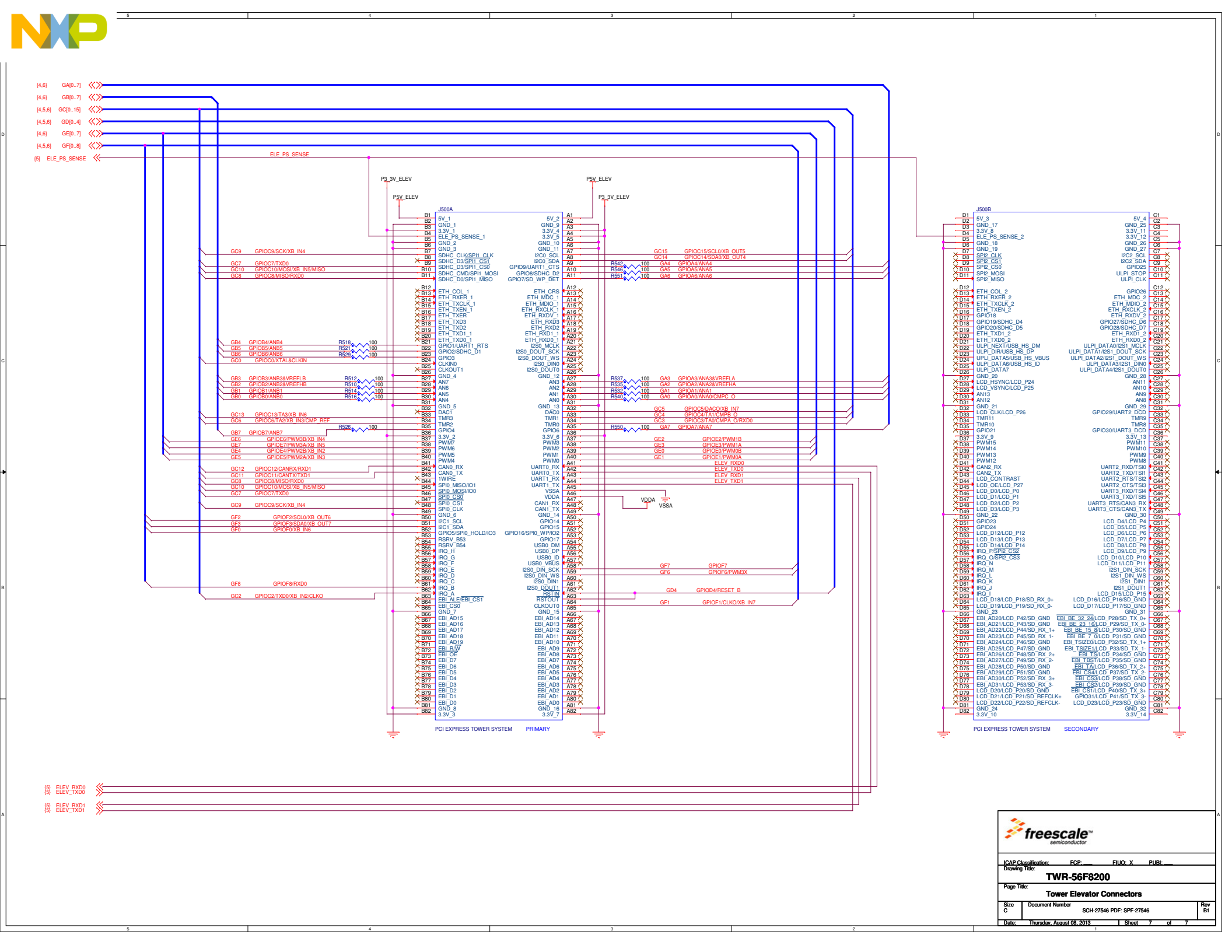
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{4,6} GB[0..7]
{4,5,6} GC[0..15]
{4,5,6} GD[0..4]
{4,6} GE[0..7]
{4,5,6} GF[0..8]
{5} ELE_PS_SENSE
ELE_PS_SENSE
P3_3V_ELEV
P5V_ELEV
P5V_ELEV
P3_3V_ELEV
J500A
PCI EXPRESS TOWER SYSTEM PRIMARY
J500B
PCI EXPRESS TOWER SYSTEM SECONDARY
VDDA
VSSA
{5,6} ELEV_RXD0
{5,6} ELEV_TXD0
{5,6} ELEV_RXD1
{5,6} ELEV_TXD1
ICAP Classification: FCP: ___ FIUO: X PUBI: ___
Drawing Title:
TWR-56F8200
Page Title:
Tower Elevator Connectors
Size C
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